CAT28F010
1 Megabit CMOS Flash Memory

FEATURES

- Fast Read Access Time: 70/90/120 ns
- Low Power CMOS Dissipation:
  - Active: 30 mA max (CMOS/TTL levels)
  - Standby: 1 mA max (TTL levels)
  - Standby: 100 µA max (CMOS levels)
- High Speed Programming:
  - 10 µs per byte
  - 2 Sec Typ Chip Program
- 0.5 Seconds Typical Chip-Erase
- 12.0V ± 5% Programming and Erase Voltage
- Stop Timer for Program/Erase
- Commercial, Industrial and Automotive Temperature Ranges
- On-Chip Address and Data Latches
- JEDEC Standard Pinouts:
  - 32-pin DIP
  - 32-pin PLCC
  - 32-pin TSOP (8 x 20)
- 100,000 Program/Erase Cycles
- 10 Year Data Retention
- Electronic Signature

DESCRIPTION

The CAT28F010 is a high speed 128K x 8-bit electrically erasable and reprogrammable Flash memory ideally suited for applications requiring in-system or after-sale code updates. Electrical erasure of the full memory contents is achieved typically within 0.5 second.

It is pin and Read timing compatible with standard EPROM and EEPROM devices. Programming and Erase are performed through an operation and verify algorithm. The instructions are input via the I/O bus, using a two write cycle scheme. Address and Data are latched to free the I/O bus and address bus during the write operation.

The CAT28F010 is manufactured using Catalyst’s advanced CMOS floating gate technology. It is designed to endure 100,000 program/erase cycles and has a data retention of 10 years. The device is available in JEDEC approved 32-pin plastic DIP, 32-pin PLCC or 32-pin TSOP packages.

BLOCK DIAGRAM

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Characteristics subject to change without notice
PIN CONFIGURATION

DIP Package (P)

- Vpp
- A16
- A15
- A14
- A7
- A6
- A5
- A4
- A3
- A2
- A1
- A0
- I/O0
- I/O1
- I/O2
- VSS

- 1
- 2
- 3
- 4
- 5
- 6
- 7
- 8
- 9
- 10
- 11
- 12
- 13
- 14
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- 16
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- 25
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- 27
- 28
- 29
- 30
- 31
- 32

PLCC Package (N)

- Vpp
- VCC
- WE
- NC
- OE
- A10
- A9
- A8
- A7
- A6
- A5
- A4
- A3
- A2
- A1
- A0
- I/O0
- I/O1
- I/O2
- VSS

- 1
- 2
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- 5
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- 7
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- 28
- 29
- 30
- 31
- 32

TSOP Package (Standard Pinout 8mm x 20mm) (T)

- A11
- A9
- A8
- A14
- NC
- WE
- VCC
- Vpp
- A16
- A15
- A12
- A7
- A6
- A5
- A4

- 1
- 2
- 3
- 4
- 5
- 6
- 7
- 8
- 9
- 10
- 11
- 12
- 13
- 14
- 15
- 16
- 17
- 18
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- 21
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- 23
- 24
- 25
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- 27
- 28
- 29
- 30
- 31
- 32

TSOP Package (Reverse Pinout) (TR)

- OE
- A10
- CE
- I/O7
- I/O6
- I/O5
- I/O4
- I/O3
- VSS
- I/O2
- I/O1
- I/O0
- A0
- A1
- A2
- A3

- 1
- 2
- 3
- 4
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- 11
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- 18
- 19
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- 23
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- 25
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- 27
- 28
- 29
- 30
- 31
- 32

PIN FUNCTIONS

<table>
<thead>
<tr>
<th>Pin Name</th>
<th>Type</th>
<th>Function</th>
</tr>
</thead>
<tbody>
<tr>
<td>A0–A16</td>
<td>Input</td>
<td>Address Inputs for memory addressing</td>
</tr>
<tr>
<td>I/O0–I/O7</td>
<td>I/O</td>
<td>Data Input/Output</td>
</tr>
<tr>
<td>CE</td>
<td>Input</td>
<td>Chip Enable</td>
</tr>
<tr>
<td>OE</td>
<td>Input</td>
<td>Output Enable</td>
</tr>
<tr>
<td>WE</td>
<td>Input</td>
<td>Write Enable</td>
</tr>
<tr>
<td>VCC</td>
<td>Voltage Supply</td>
<td></td>
</tr>
<tr>
<td>VSS</td>
<td>Ground</td>
<td></td>
</tr>
<tr>
<td>VPP</td>
<td>Program/Erase Voltage Supply</td>
<td></td>
</tr>
</tbody>
</table>
**ABSOLUTE MAXIMUM RATINGS**

- **Temperature Under Bias** ............... –55°C to +95°C
- **Storage Temperature** ................... –65°C to +150°C
- **Voltage on Any Pin with Respect to Ground** (1) .......... –2.0V to +V CC + 2.0V
- **Voltage on Pin A9 with Respect to Ground** (1) ........... –2.0V to +13.5V
- **V PP with Respect to Ground during Program/Erase** (1) .......... –2.0V to +14.0V
- **V CC with Respect to Ground** .......... –2.0V to +7.0V
- **Package Power Dissipation Capability** (T A = 25°C) ...................... 1.0 W
- **Lead Soldering Temperature** (10 secs) ............... 300°C
- **Output Short Circuit Current** (2) .......... 100 mA

**RELIABILITY CHARACTERISTICS**

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Min.</th>
<th>Max.</th>
<th>Units</th>
<th>Test Method</th>
</tr>
</thead>
<tbody>
<tr>
<td>N END(3)</td>
<td>Endurance</td>
<td>100K</td>
<td></td>
<td>Cycles/Byte</td>
<td>MIL-STD-883, Test Method 1033</td>
</tr>
<tr>
<td>T DR(3)</td>
<td>Data Retention</td>
<td>10</td>
<td></td>
<td>Years</td>
<td>MIL-STD-883, Test Method 1008</td>
</tr>
<tr>
<td>V ZAP(3)</td>
<td>ESD Susceptibility</td>
<td>2000</td>
<td></td>
<td>Volts</td>
<td>MIL-STD-883, Test Method 3015</td>
</tr>
<tr>
<td>I LTH(3)(4)</td>
<td>Latch-Up</td>
<td>100</td>
<td></td>
<td>mA</td>
<td>JEDEC Standard 17</td>
</tr>
</tbody>
</table>

**CAPACITANCE**  

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Test</th>
<th>Limits</th>
<th>Units</th>
<th>Conditions</th>
</tr>
</thead>
<tbody>
<tr>
<td>C IN(3)</td>
<td>Input Pin Capacitance</td>
<td>Min</td>
<td>6</td>
<td>pF</td>
</tr>
<tr>
<td>C OUT(3)</td>
<td>Output Pin Capacitance</td>
<td>Max</td>
<td>10</td>
<td>pF</td>
</tr>
<tr>
<td>C VPP(3)</td>
<td>V PP Supply Capacitance</td>
<td>Min</td>
<td>25</td>
<td>pF</td>
</tr>
</tbody>
</table>

**COMMENT**

Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions outside of those listed in the operational sections of this specification is not implied. Exposure to any absolute maximum rating for extended periods may affect device performance and reliability.

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**Note:**

1. The minimum DC input voltage is –0.5V. During transitions, inputs may undershoot to –2.0V for periods of less than 20 ns. Maximum DC voltage on output pins is V CC +0.5V, which may overshoot to V CC + 2.0V for periods of less than 20ns.
2. Output shorted for no more than one second. No more than one output shorted at a time.
3. This parameter is tested initially and after a design or process change that affects the parameter.
4. Latch-up protection is provided for stresses up to 100 mA on address and data pins from –1V to V CC +1V.
## D.C. OPERATING CHARACTERISTICS

*V<sub>CC</sub> = +5V ±10%, unless otherwise specified.*

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Limits</th>
<th>Test Conditions</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td>Min.</td>
<td>Max.</td>
</tr>
<tr>
<td>I&lt;sub&gt;LI&lt;/sub&gt;</td>
<td>Input Leakage Current</td>
<td>±1</td>
<td>µA</td>
</tr>
<tr>
<td>I&lt;sub&gt;LO&lt;/sub&gt;</td>
<td>Output Leakage Current</td>
<td>±1</td>
<td>µA</td>
</tr>
<tr>
<td>I&lt;sub&gt;SB1&lt;/sub&gt;</td>
<td>V&lt;sub&gt;CC&lt;/sub&gt; Standby Current CMOS</td>
<td>100</td>
<td>µA</td>
</tr>
<tr>
<td>I&lt;sub&gt;SB2&lt;/sub&gt;</td>
<td>V&lt;sub&gt;CC&lt;/sub&gt; Standby Current TTL</td>
<td>1</td>
<td>mA</td>
</tr>
<tr>
<td>I&lt;sub&gt;CC1&lt;/sub&gt;</td>
<td>V&lt;sub&gt;CC&lt;/sub&gt; Active Read Current</td>
<td>30</td>
<td>mA</td>
</tr>
<tr>
<td>I&lt;sub&gt;CC2&lt;/sub&gt;(1)</td>
<td>V&lt;sub&gt;CC&lt;/sub&gt; Programming Current</td>
<td>15</td>
<td>mA</td>
</tr>
<tr>
<td>I&lt;sub&gt;CC3&lt;/sub&gt;(1)</td>
<td>V&lt;sub&gt;CC&lt;/sub&gt; Erase Current</td>
<td>15</td>
<td>mA</td>
</tr>
<tr>
<td>I&lt;sub&gt;CC4&lt;/sub&gt;(1)</td>
<td>V&lt;sub&gt;CC&lt;/sub&gt; Prog./Erase Verify Current</td>
<td>15</td>
<td>mA</td>
</tr>
<tr>
<td>I&lt;sub&gt;PPS&lt;/sub&gt;</td>
<td>V&lt;sub&gt;PP&lt;/sub&gt; Standby Current</td>
<td>±10</td>
<td>µA</td>
</tr>
<tr>
<td>I&lt;sub&gt;PP1&lt;/sub&gt;</td>
<td>V&lt;sub&gt;PP&lt;/sub&gt; Read Current</td>
<td>200</td>
<td>µA</td>
</tr>
<tr>
<td>I&lt;sub&gt;PP2&lt;/sub&gt;(1)</td>
<td>V&lt;sub&gt;PP&lt;/sub&gt; Programming Current</td>
<td>30</td>
<td>mA</td>
</tr>
<tr>
<td>I&lt;sub&gt;PP3&lt;/sub&gt;(1)</td>
<td>V&lt;sub&gt;PP&lt;/sub&gt; Erase Current</td>
<td>30</td>
<td>mA</td>
</tr>
<tr>
<td>I&lt;sub&gt;PP4&lt;/sub&gt;(1)</td>
<td>V&lt;sub&gt;PP&lt;/sub&gt; Prog./Erase Verify Current</td>
<td>5</td>
<td>mA</td>
</tr>
<tr>
<td>V&lt;sub&gt;IL&lt;/sub&gt;</td>
<td>Input Low Level TTL</td>
<td>−0.5</td>
<td>0.8</td>
</tr>
<tr>
<td>V&lt;sub&gt;ILC&lt;/sub&gt;</td>
<td>Input Low Level CMOS</td>
<td>−0.5</td>
<td>0.8</td>
</tr>
<tr>
<td>V&lt;sub&gt;OL&lt;/sub&gt;</td>
<td>Output Low Level</td>
<td>0.45</td>
<td>V</td>
</tr>
<tr>
<td>V&lt;sub&gt;IH&lt;/sub&gt;</td>
<td>Input High Level TTL</td>
<td>2</td>
<td>V&lt;sub&gt;CC&lt;/sub&gt;+0.5</td>
</tr>
<tr>
<td>V&lt;sub&gt;IHC&lt;/sub&gt;</td>
<td>Input High Level CMOS</td>
<td>V&lt;sub&gt;CC&lt;/sub&gt;*0.7</td>
<td>V&lt;sub&gt;CC&lt;/sub&gt;+0.5</td>
</tr>
<tr>
<td>V&lt;sub&gt;OH1&lt;/sub&gt;</td>
<td>Output High Level TTL</td>
<td>2.4</td>
<td>V</td>
</tr>
<tr>
<td>V&lt;sub&gt;OH2&lt;/sub&gt;</td>
<td>Output High Level CMOS</td>
<td>V&lt;sub&gt;CC&lt;/sub&gt;−0.4</td>
<td>V</td>
</tr>
<tr>
<td>V&lt;sub&gt;ID&lt;/sub&gt;</td>
<td>A&lt;sub&gt;9&lt;/sub&gt; Signature Voltage</td>
<td>11.4</td>
<td>13</td>
</tr>
<tr>
<td>I&lt;sub&gt;ID&lt;/sub&gt;(1)</td>
<td>A&lt;sub&gt;9&lt;/sub&gt; Signature Current</td>
<td>200</td>
<td>µA</td>
</tr>
<tr>
<td>V&lt;sub&gt;LO&lt;/sub&gt;</td>
<td>V&lt;sub&gt;CC&lt;/sub&gt; Erase/Prog. Lockout Voltage</td>
<td>2.5</td>
<td>V</td>
</tr>
</tbody>
</table>

**Note:**

(1) This parameter is tested initially and after a design or process change that affects the parameter.
SUPPLY CHARACTERISTICS

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Limits</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>V_{CC}</td>
<td>V_{CC} Supply Voltage</td>
<td>Min: 4.5, Max: 5.5</td>
<td>V</td>
</tr>
<tr>
<td>V_{PP}</td>
<td>V_{PP} During Read Operations</td>
<td>Min: 0, Max: 6.5</td>
<td>V</td>
</tr>
<tr>
<td>V_{PPH}</td>
<td>V_{PP} During Read/Erase/Program</td>
<td>Min: 11.4, Max: 12.6</td>
<td>V</td>
</tr>
</tbody>
</table>

A.C. CHARACTERISTICS, Read Operation

V_{CC} = +5V ±10%, unless otherwise specified.

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Standard</th>
<th>Parameter</th>
<th>28F010-70(8)</th>
<th>28F010-90(7)</th>
<th>28F010-12(7)</th>
</tr>
</thead>
<tbody>
<tr>
<td>t_{AVAV}</td>
<td>t_{RC}</td>
<td>Read Cycle Time</td>
<td>Min: 70, Max: 90</td>
<td>Min: 120, Max: 150</td>
<td>ns</td>
</tr>
<tr>
<td>t_{ELOV}</td>
<td>t_{CE}</td>
<td>CE Access Time</td>
<td>Min: 70, Max: 90</td>
<td>Min: 120, Max: 150</td>
<td>ns</td>
</tr>
<tr>
<td>t_{AVOV}</td>
<td>t_{ACC}</td>
<td>Address Access Time</td>
<td>Min: 70, Max: 90</td>
<td>Min: 120, Max: 150</td>
<td>ns</td>
</tr>
<tr>
<td>t_{GLOV}</td>
<td>t_{OE}</td>
<td>OE Access Time</td>
<td>Min: 28, Max: 35</td>
<td>Min: 45, Max: 50</td>
<td>ns</td>
</tr>
<tr>
<td>t_{AXOX}</td>
<td>t_{OH}</td>
<td>Output Hold from Address OE/CE Change</td>
<td>0, 0, 0 ns</td>
<td></td>
<td></td>
</tr>
<tr>
<td>t_{GLOX}</td>
<td>t_{OLZ} (1)(6)</td>
<td>OE to Output in Low-Z</td>
<td>0, 0, 0 ns</td>
<td></td>
<td></td>
</tr>
<tr>
<td>t_{ELZX}</td>
<td>t_{IZ} (1)(6)</td>
<td>CE to Output in Low-Z</td>
<td>0, 0, 0 ns</td>
<td></td>
<td></td>
</tr>
<tr>
<td>t_{GHOZ}</td>
<td>t_{DF} (1)(2)</td>
<td>OE High to Output High-Z</td>
<td>Min: 20, Max: 30, Max: 40</td>
<td>ns</td>
<td></td>
</tr>
<tr>
<td>t_{EHQZ}</td>
<td>t_{DF} (1)(2)</td>
<td>CE High to Output High-Z</td>
<td>Min: 20, Max: 30, Max: 40</td>
<td>ns</td>
<td></td>
</tr>
<tr>
<td>t_{WHGL (1)}</td>
<td>-</td>
<td>Write Recovery Time Before Read</td>
<td>6, 6, 6</td>
<td>µs</td>
<td></td>
</tr>
</tbody>
</table>

Note:
(1) This parameter is tested initially and after a design or process change that affects the parameter.
(2) Output floating (High-Z) is defined as the state where the external data line is no longer driven by the output buffer.
(3) Input Rise and Fall Times (10% to 90%) < 10 ns.
(4) Input Pulse Levels = 0.45V and 2.4V. For High Speed Input Pulse Levels 0.0V and 3.0V.
(5) Input and Output Timing Reference = 0.8V and 2.0V. For High Speed Input and Output Timing Reference = 1.5V.
(6) Low-Z is defined as the state where the external data may be driven by the output buffer but may not be valid.
(7) For load and reference points, see Fig. 1.
(8) For load and reference points, see Fig. 2.
A.C. CHARACTERISTICS, Read Operation

$V_{CC} = +5V \pm 10\%$, unless otherwise specified.

<table>
<thead>
<tr>
<th>JEDEC Symbol</th>
<th>Standard Symbol</th>
<th>Parameter</th>
<th>28F010-70</th>
<th>28F010-90</th>
<th>28F010-12</th>
</tr>
</thead>
<tbody>
<tr>
<td>$t_{AVAV}$</td>
<td>$t_{WC}$</td>
<td>Write Cycle Time</td>
<td>70</td>
<td>90</td>
<td>120</td>
</tr>
<tr>
<td>$t_{AVWL}$</td>
<td>$t_{AS}$</td>
<td>Address Setup Time</td>
<td>0</td>
<td>0</td>
<td>0</td>
</tr>
<tr>
<td>$t_{WLAX}$</td>
<td>$t_{AH}$</td>
<td>Address Hold Time</td>
<td>40</td>
<td>40</td>
<td>40</td>
</tr>
<tr>
<td>$t_{DVWH}$</td>
<td>$t_{DS}$</td>
<td>Data Setup Time</td>
<td>40</td>
<td>40</td>
<td>40</td>
</tr>
<tr>
<td>$t_{WHDX}$</td>
<td>$t_{DH}$</td>
<td>Data Hold Time</td>
<td>10</td>
<td>10</td>
<td>10</td>
</tr>
<tr>
<td>$t_{ELWL}$</td>
<td>$t_{CS}$</td>
<td>CE Setup Time</td>
<td>0</td>
<td>0</td>
<td>0</td>
</tr>
<tr>
<td>$t_{WHEH}$</td>
<td>$t_{CH}$</td>
<td>CE Hold Time</td>
<td>0</td>
<td>0</td>
<td>0</td>
</tr>
<tr>
<td>$t_{WLWH}$</td>
<td>$t_{WP}$</td>
<td>WE Pulse Width</td>
<td>40</td>
<td>40</td>
<td>40</td>
</tr>
<tr>
<td>$t_{WHWL}$</td>
<td>$t_{WPH}$</td>
<td>WE High Pulse Width</td>
<td>20</td>
<td>20</td>
<td>20</td>
</tr>
<tr>
<td>$t_{WHWH1}$</td>
<td></td>
<td>Program Pulse Width</td>
<td>10</td>
<td>10</td>
<td>10</td>
</tr>
<tr>
<td>$t_{WHWH2}$</td>
<td></td>
<td>Erase Pulse Width</td>
<td>9.5</td>
<td>9.5</td>
<td>9.5</td>
</tr>
<tr>
<td>$t_{WHGL}$</td>
<td></td>
<td>Write Recovery Time Before Read</td>
<td>6</td>
<td>6</td>
<td>6</td>
</tr>
<tr>
<td>$t_{GHWL}$</td>
<td></td>
<td>Read Recovery Time Before Write</td>
<td>0</td>
<td>0</td>
<td>0</td>
</tr>
<tr>
<td>$t_{VPEL}$</td>
<td></td>
<td>$V_{PP}$ Setup Time to CE</td>
<td>100</td>
<td>100</td>
<td>100</td>
</tr>
</tbody>
</table>

ERASE AND PROGRAMMING PERFORMANCE

<table>
<thead>
<tr>
<th>Parameter</th>
<th>28F010-55</th>
<th>28F010-70</th>
<th>28F010-90</th>
<th>28F010-12</th>
</tr>
</thead>
<tbody>
<tr>
<td>Chip Erase Time</td>
<td>0.5 10</td>
<td>0.5 10</td>
<td>0.5 10</td>
<td>0.5 10</td>
</tr>
<tr>
<td>Chip Program Time</td>
<td>2 12.5</td>
<td>2 12.5</td>
<td>2 12.5</td>
<td>2 12.5</td>
</tr>
</tbody>
</table>

Note:

1. Please refer to Supply characteristics for the value of $V_{PPH}$ and $V_{PPL}$. The $V_{PP}$ supply can be either hardwired or switched. If $V_{PP}$ is switched, $V_{PPL}$ can be ground, less than $V_{CC} + 2.0V$ or a no connect with a resistor tied to ground.
2. Program and Erase operations are controlled by internal stop timers.
3. 'Typicals' are not guaranteed, but based on characterization data. Data taken at 25°C, 12.0V $V_{PP}$.
4. Minimum byte programming time (excluding system overhead) is 16 $\mu$s (10 $\mu$s program + 6 $\mu$s write recovery), while maximum is 400 $\mu$s/byte (16 $\mu$s x 25 loops). Max chip programming time is specified lower than the worst case allowed by the programming algorithm since most bytes program significantly faster than the worst case byte.
5. Excludes 00H Programming prior to Erasure.
## FUNCTION TABLE (1)

<table>
<thead>
<tr>
<th>Mode</th>
<th>CE</th>
<th>OE</th>
<th>WE</th>
<th>V&lt;sub&gt;PP&lt;/sub&gt;</th>
<th>I/O</th>
<th>Notes</th>
</tr>
</thead>
<tbody>
<tr>
<td>Read</td>
<td>V&lt;sub&gt;IL&lt;/sub&gt;</td>
<td>V&lt;sub&gt;IL&lt;/sub&gt;</td>
<td>V&lt;sub&gt;IH&lt;/sub&gt;</td>
<td>V&lt;sub&gt;PPL&lt;/sub&gt;</td>
<td>D&lt;sub&gt;OUT&lt;/sub&gt;</td>
<td></td>
</tr>
<tr>
<td>Output Disable</td>
<td>V&lt;sub&gt;IL&lt;/sub&gt;</td>
<td>V&lt;sub&gt;IH&lt;/sub&gt;</td>
<td>V&lt;sub&gt;IH&lt;/sub&gt;</td>
<td>X</td>
<td>High-Z</td>
<td></td>
</tr>
<tr>
<td>Standby</td>
<td>V&lt;sub&gt;IH&lt;/sub&gt;</td>
<td>X</td>
<td>X</td>
<td>V&lt;sub&gt;PPL&lt;/sub&gt;</td>
<td>High-Z</td>
<td></td>
</tr>
<tr>
<td>Signature (MFG)</td>
<td>V&lt;sub&gt;IL&lt;/sub&gt;</td>
<td>V&lt;sub&gt;IL&lt;/sub&gt;</td>
<td>V&lt;sub&gt;IH&lt;/sub&gt;</td>
<td>X</td>
<td>31H</td>
<td>A₀ = V&lt;sub&gt;IL&lt;/sub&gt;, A₉ = 12V</td>
</tr>
<tr>
<td>Signature (Device)</td>
<td>V&lt;sub&gt;IL&lt;/sub&gt;</td>
<td>V&lt;sub&gt;IL&lt;/sub&gt;</td>
<td>V&lt;sub&gt;IH&lt;/sub&gt;</td>
<td>X</td>
<td>B4H</td>
<td>A₀ = V&lt;sub&gt;IH&lt;/sub&gt;, A₉ = 12V</td>
</tr>
<tr>
<td>Program/Erase</td>
<td>V&lt;sub&gt;IL&lt;/sub&gt;</td>
<td>V&lt;sub&gt;IH&lt;/sub&gt;</td>
<td>V&lt;sub&gt;IL&lt;/sub&gt;</td>
<td>V&lt;sub&gt;PPH&lt;/sub&gt;</td>
<td>D&lt;sub&gt;IN&lt;/sub&gt;</td>
<td>See Command Table</td>
</tr>
<tr>
<td>Write Cycle</td>
<td>V&lt;sub&gt;IL&lt;/sub&gt;</td>
<td>V&lt;sub&gt;IH&lt;/sub&gt;</td>
<td>V&lt;sub&gt;IL&lt;/sub&gt;</td>
<td>V&lt;sub&gt;PPH&lt;/sub&gt;</td>
<td>D&lt;sub&gt;IN&lt;/sub&gt;</td>
<td>During Write Cycle</td>
</tr>
<tr>
<td>Read Cycle</td>
<td>V&lt;sub&gt;IL&lt;/sub&gt;</td>
<td>V&lt;sub&gt;IL&lt;/sub&gt;</td>
<td>V&lt;sub&gt;IH&lt;/sub&gt;</td>
<td>V&lt;sub&gt;PPH&lt;/sub&gt;</td>
<td>D&lt;sub&gt;OUT&lt;/sub&gt;</td>
<td>During Write Cycle</td>
</tr>
</tbody>
</table>

## WRITE COMMAND TABLE

Commands are written into the command register in one or two write cycles. The command register can be altered only when V<sub>PP</sub> is high and the instruction byte is latched on the rising edge of WE. Write cycles also internally latch addresses and data required for programming and erase operations.

<table>
<thead>
<tr>
<th>Mode</th>
<th>Pins</th>
<th>First Bus Cycle</th>
<th>Second Bus Cycle</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td>Operation</td>
<td>Address</td>
</tr>
<tr>
<td>Set Read</td>
<td>Write</td>
<td>X</td>
<td>00H</td>
</tr>
<tr>
<td>Read Sig. (MFG)</td>
<td>Write</td>
<td>X</td>
<td>90H</td>
</tr>
<tr>
<td>Read Sig. (Device)</td>
<td>Write</td>
<td>X</td>
<td>90H</td>
</tr>
<tr>
<td>Erase</td>
<td>Write</td>
<td>X</td>
<td>20H</td>
</tr>
<tr>
<td>Erase Verify</td>
<td>Write</td>
<td>A&lt;sub&gt;IN&lt;/sub&gt;</td>
<td>A0H</td>
</tr>
<tr>
<td>Program</td>
<td>Write</td>
<td>X</td>
<td>40H</td>
</tr>
<tr>
<td>Program Verify</td>
<td>Write</td>
<td>X</td>
<td>C0H</td>
</tr>
<tr>
<td>Reset</td>
<td>Write</td>
<td>X</td>
<td>FFH</td>
</tr>
</tbody>
</table>

**Note:**
(1) Logic Levels: X = Logic ‘Do not care’ (V<sub>IH</sub>, V<sub>IL</sub>, V<sub>PPL</sub>, V<sub>PPH</sub>)
READ OPERATIONS

Read Mode
A Read operation is performed with both \( \overline{CE} \) and \( \overline{OE} \) low and with \( \overline{WE} \) high. \( V_{PP} \) can be either high or low, however, if \( V_{PP} \) is high, the Set READ command has to be sent before reading data (see Write Operations). The data retrieved from the I/O pins reflects the contents of the memory location corresponding to the state of the 17 address pins. The respective timing waveforms for the read operation are shown in Figure 3. Refer to the AC Read characteristics for specific timing parameters.

Signature Mode
The signature mode allows the user to identify the IC manufacturer and the type of device while the device resides in the target system. This mode can be activated in either of two ways; through the conventional method of applying a high voltage (12V) to address pin \( A_9 \) or by sending an instruction to the command register (see Write Operations).

Standby Mode
With \( \overline{CE} \) at a logic-high level, the CAT28F010 is placed in a standby mode where most of the device circuitry is disabled, thereby substantially reducing power consumption. The outputs are placed in a high-impedance state.

The conventional mode is entered as a regular READ mode by driving the \( \overline{CE} \) and \( \overline{OE} \) pins low (with \( \overline{WE} \) high), and applying the required high voltage on address pin \( A_9 \) while all other address lines are held at \( V_{IL} \).

A Read cycle from address 0000H retrieves the binary code for the IC manufacturer on outputs I/O₀ to I/O₇:

CATALYST Code = 00110001 (31H)

A Read cycle from address 0001H retrieves the binary code for the device on outputs I/O₀ to I/O₇:

28F010 Code = 1011 0100 (B4H)
WRITE OPERATIONS

The following operations are initiated by observing the sequence specified in the Write Command Table.

Read Mode

The device can be put into a standard READ mode by initiating a write cycle with 00H on the data bus. The subsequent read cycles will be performed similar to a standard EPROM or E²PROM Read.

Signature Mode

An alternative method for reading device signature (see Read Operations Signature Mode), is initiated by writing the code 90H into the command register while keeping VPP high. A read cycle from address 0000H with CE and OE low (and WE high) will output the device signature.

CATALYST Code = 00110001 (31H)

A Read cycle from address 0001H retrieves the binary code for the device on outputs I/O 0 to I/O 7.

28F010 Code = 1011 0100 (B4H)
Figure 5. Chip Erase Algorithm(1)

Note:
(1) The algorithm MUST BE FOLLOWED to ensure proper and reliable operation of the device.
Erase Mode
During the first Write cycle, the command 20H is written into the command register. In order to commence the erase operation, the identical command of 20H has to be written again into the register. This two-step process ensures against accidental erasure of the memory contents. The final erase cycle will be stopped at the rising edge of WE, at which time the Erase Verify command (A0H) is sent to the command register. During this cycle, the address to be verified is sent to the address bus and latched when WE goes low. An integrated stop timer allows for automatic timing control over this operation, eliminating the need for a maximum erase timing specification. Refer to AC Characteristics (Program/Erase) for specific timing parameters.

Erase-Verify Mode
The Erase-verify operation is performed on every byte after each erase pulse to verify that the bits have been erased.

Programming Mode
The programming operation is initiated using the programming algorithm of Figure 7. During the first write cycle, the command 40H is written into the command register. During the second write cycle, the address of the memory location to be programmed is latched on the falling edge of WE, while the data is latched on the rising edge of WE. The program operation terminates with the next rising edge of WE. An integrated stop timer allows for automatic timing control over this operation, eliminating the need for a maximum program timing specification. Refer to AC Characteristics (Program/Erase) for specific timing parameters.

Figure 6. A.C. Timing for Programming Operation
Figure 7. Programming Algorithm (1)

START PROGRAMMING

APPLY VppH

INITIALIZE ADDRESS

PLSCNT = 0

WRITE SETUP PROG. COMMAND

WRITE PROG. CMD ADDR AND DATA

TIME OUT 10μs

WRITE PROGRAM VERIFY COMMAND

TIME OUT 6μs

READ DATA FROM DEVICE

VERIFY DATA?

INC PLSCNT = 25?

INCREMENT ADDRESS

LAST ADDRESS?

WRITE READ COMMAND

APPLY VpPL

PROGRAMMING COMPLETED

PROGRAM ERROR

BUS OPERATION | COMMAND | COMMENTS
--- | --- | ---
STANDBY | WRITE SETUP | Vpp RAMPS TO VppH (OR Vpp HARDWIRED)
 | | INITIALIZE ADDRESS
 | | INITIALIZE PULSE COUNT PLSCNT = PULSE COUNT
1ST WRITE CYCLE | WRITE prog. command | DATA = 40H
2ND WRITE CYCLE | PROGRAM | VALID ADDRESS AND DATA
 | | WAIT
1ST WRITE CYCLE | PROGRAM VERIFY | DATA = C0H
 | | WAIT
READ | READ | READ BYTE TO VERIFY PROGRAMMING
 | | COMPARE DATA OUTPUT TO DATA EXPECTED
1ST WRITE CYCLE | READ | DATA = 00H SETS THE REGISTER FOR READ OPERATION
 | | Vpp RAMPS TO VpPL (OR Vpp HARDWIRED)

Note:
(1) The algorithm MUST BE FOLLOWED to ensure proper and reliable operation of the device.
Program-Verify Mode
A Program-verify cycle is performed to ensure that all bits have been correctly programmed following each byte programming operation. The specific address is already latched from the write cycle just completed, and stays latched until the verify is completed. The Program-verify operation is initiated by writing C0H into the command register. An internal reference generates the necessary high voltages so that the user does not need to modify VCC. Refer to AC Characteristics (Program/Erase) for specific timing parameters.

Abort/Reset
An Abort/Reset command is available to allow the user to safely abort an erase or program sequence. Two consecutive program cycles with FFH on the data bus will abort an erase or a program operation. The abort/reset operation can interrupt at any time in a program or erase operation and the device is reset to the Read Mode.

POWER UP/DOWN PROTECTION
The CAT28F010 offers protection against inadvertent programming during VPP and VCC power transitions. When powering up the device there is no power-on sequencing necessary. In other words, VPP and VCC may power up in any order. Additionally VPP may be hardwired to VPPH independent of the state of VCC and any power up/down cycling. The internal command register of the CAT28F010 is reset to the Read Mode on power up.

POWER SUPPLY DECOUPLING
To reduce the effect of transient power supply voltage spikes, it is good practice to use a 0.1μF ceramic capacitor between VCC and VSS and VPP and VSS. These high-frequency capacitors should be placed as close as possible to the device for optimum decoupling.

Figure 8. Alternate A.C. Timing for Program Operation
A.C. CHARACTERISTICS, Read Operation

V_{CC} = +5V \pm 10\%, unless otherwise specified.

<table>
<thead>
<tr>
<th>JEDEC Symbol</th>
<th>Standard Symbol</th>
<th>Parameter</th>
<th>28F010-70</th>
<th>28F010-90</th>
<th>28F010-12</th>
</tr>
</thead>
<tbody>
<tr>
<td>t_{AVAV}</td>
<td>t_{WC}</td>
<td>Write Cycle Time</td>
<td>70</td>
<td>90</td>
<td>120</td>
</tr>
<tr>
<td>t_{AVEL}</td>
<td>t_{AS}</td>
<td>Address Setup Time</td>
<td>0</td>
<td>0</td>
<td>0</td>
</tr>
<tr>
<td>t_{ELAX}</td>
<td>t_{AH}</td>
<td>Address Hold Time</td>
<td>40</td>
<td>40</td>
<td>40</td>
</tr>
<tr>
<td>t_{DVEH}</td>
<td>t_{DS}</td>
<td>Data Setup Time</td>
<td>40</td>
<td>40</td>
<td>40</td>
</tr>
<tr>
<td>t_{EHDX}</td>
<td>t_{DH}</td>
<td>Data Hold Time</td>
<td>10</td>
<td>10</td>
<td>10</td>
</tr>
<tr>
<td>t_{EHGL}</td>
<td>-</td>
<td>Write Recovery Time Before Read</td>
<td>0</td>
<td>0</td>
<td>0</td>
</tr>
<tr>
<td>t_{GHEL}</td>
<td>-</td>
<td>Read Recovery Time Before Write</td>
<td>0</td>
<td>0</td>
<td>0</td>
</tr>
<tr>
<td>t_{WLEL}</td>
<td>t_{WS}</td>
<td>WE Setup time Before CE</td>
<td>0</td>
<td>0</td>
<td>0</td>
</tr>
<tr>
<td>t_{EHWH}</td>
<td>-</td>
<td>WE Hold Time After CE</td>
<td>0</td>
<td>0</td>
<td>0</td>
</tr>
<tr>
<td>t_{LEH}</td>
<td>t_{CP}</td>
<td>Write Pulse Width</td>
<td>40</td>
<td>40</td>
<td>40</td>
</tr>
<tr>
<td>t_{HEH}</td>
<td>t_{CPH}</td>
<td>Write Pulse Width High</td>
<td>20</td>
<td>20</td>
<td>20</td>
</tr>
<tr>
<td>t_{VPEL}</td>
<td>-</td>
<td>V_{PP} Setup Time to CE Low</td>
<td>100</td>
<td>100</td>
<td>100</td>
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ORDERING INFORMATION

<table>
<thead>
<tr>
<th>Prefix</th>
<th>Device #</th>
<th>Suffix</th>
</tr>
</thead>
<tbody>
<tr>
<td>CAT</td>
<td>28F010</td>
<td>N</td>
</tr>
<tr>
<td></td>
<td></td>
<td>I</td>
</tr>
<tr>
<td></td>
<td></td>
<td>-90</td>
</tr>
<tr>
<td></td>
<td></td>
<td>T</td>
</tr>
</tbody>
</table>

Product Number

Temperature Range
Blank = Commercial (0˚C to +70˚C)
I = Industrial (-40˚C to +85˚C)
A = Automotive (-40˚C to +105˚C)*

Package
N: PLCC
P: PDIP
T: TSOP (8mmx20mm)
TR: TSOP (Reverse Pinout)

Tape & Reel
T: 500/Reel
Speed
70: 70ns
90: 90ns
12: 120ns

* -40˚ to +125˚ is available upon request.

Note:
(1) The device used in the above example is a CAT28F010NI-90T(PLCC, Industrial Temperature, 90 ns access time, Tape & Reel).